

Technology Roadmaps

What Value for PSMC?

LMI

PSMC – Mesa, AZ

Dec 3-6, 2013

The Purpose of Technology Roadmapping

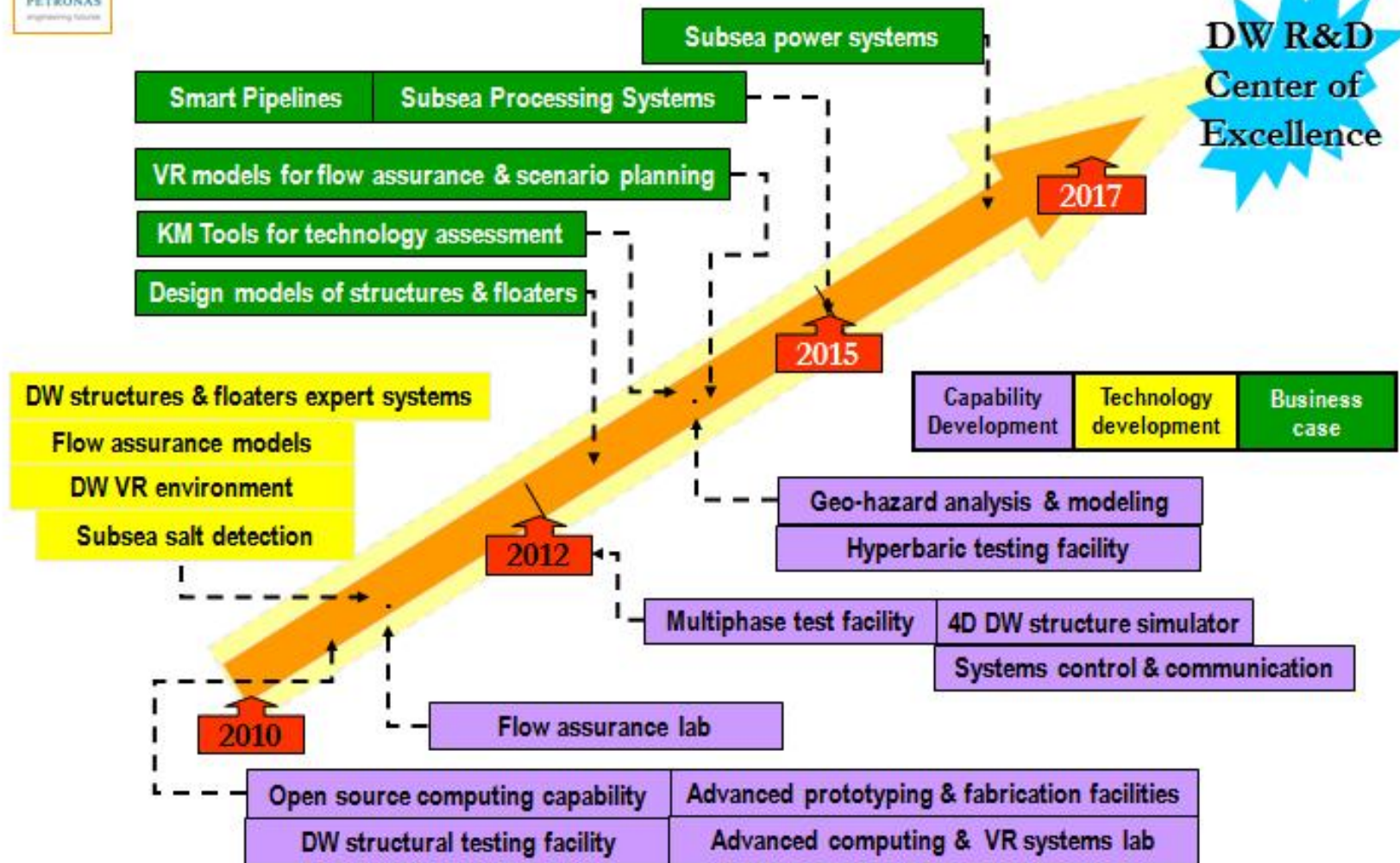
- **Product planning**
 - This is the most common type of a technology roadmap; linking the insertion of technologies into products.
- **Program planning**
 - This type is more directed to the implementation of strategy and related to project planning.

Technology Roadmap

- A plan that matches goals with specific technology solutions.
- Applies to a new product, process, or emerging technology.
- Helps reach a consensus about needs and the technologies required to satisfy those needs.
- Provides a mechanism to forecast technology developments and provides a framework to plan and coordinate technology developments.

Deepwater Technology Roadmap

DW R&D
Center of
Excellence



Process

Technology roadmapping fits into corporate strategic planning, technology planning, and business development.

Three critical elements should be connected:

- needs,
- products
- technology.

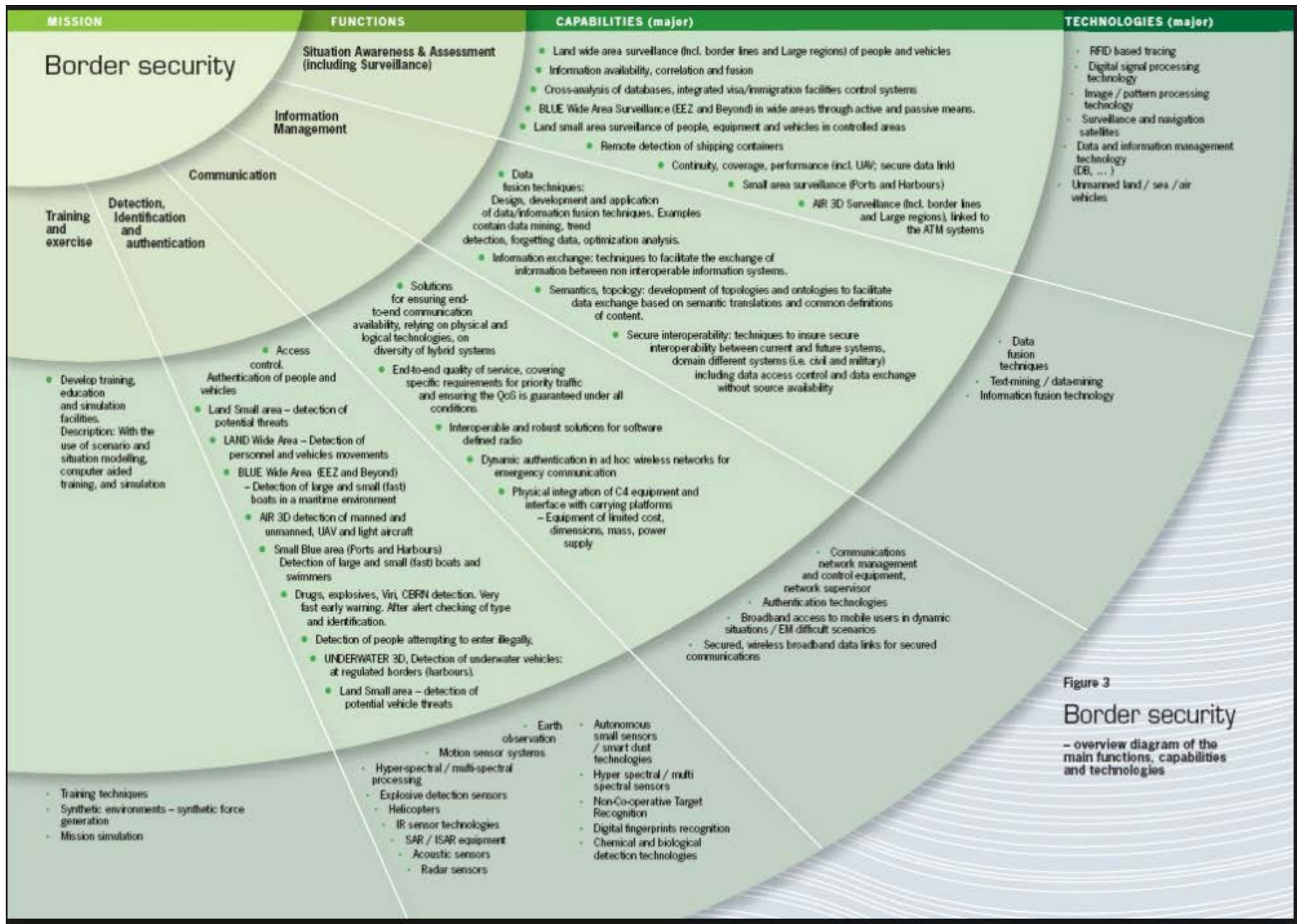


Figure 3
Border security
– overview diagram of the main functions, capabilities and technologies

Preliminary Steps

- 1. satisfy essential conditions,*
- 2. provide leadership / sponsorship*
- 3. define the scope and boundaries*

Essential Conditions

1. A need for the technology roadmap,
2. Input and participation from several different parts of the organization

Leadership / Sponsorship

- Committed leadership
 - time and effort is involved in creating the technology roadmap.
- Leadership and sponsorship
 - should come from one of the participants
- Roadmap
 - used to make resource allocation decisions.

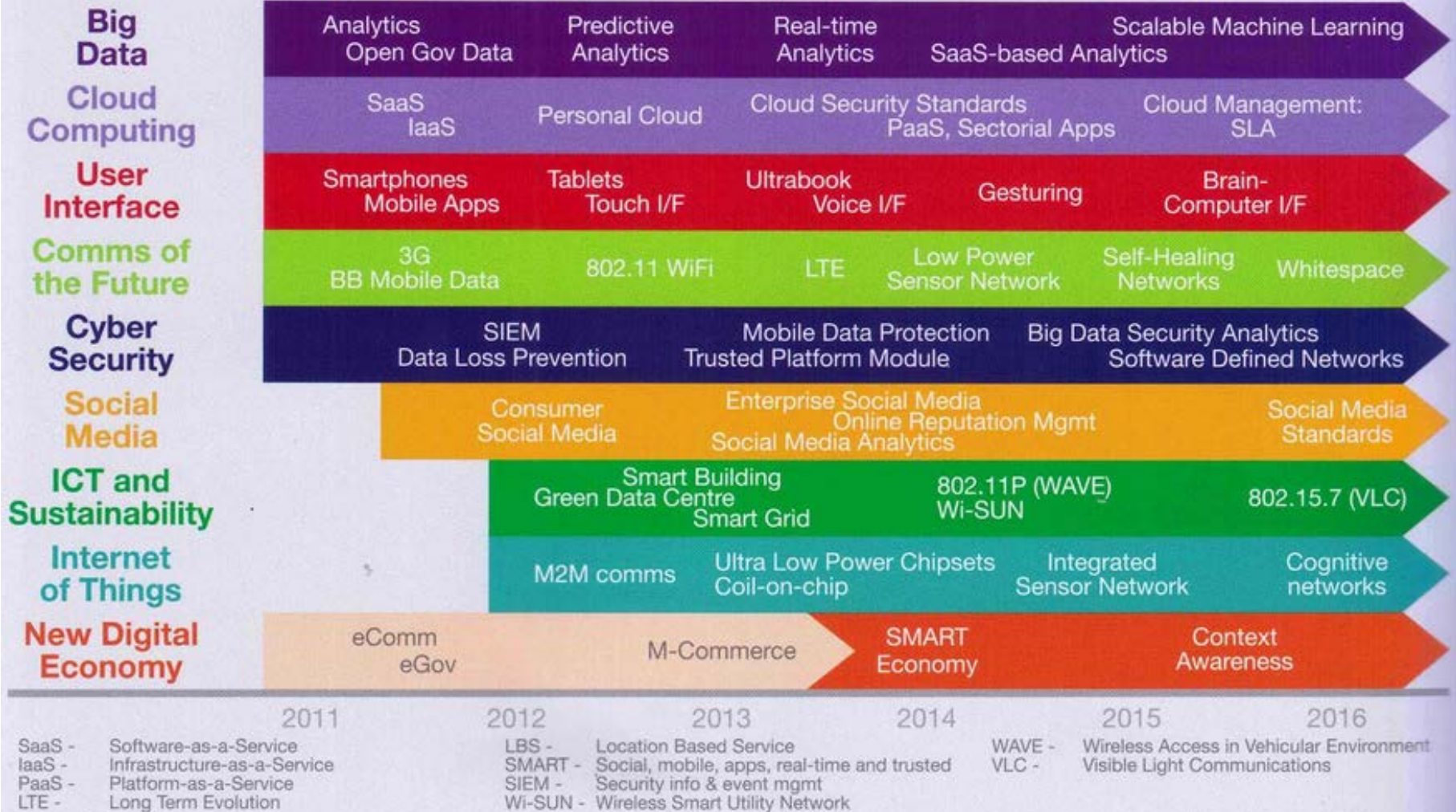
Define the scope and boundaries for the technology roadmap

- A vision that the roadmap can support
- Boundaries and the scope of the roadmap
- Planning horizon and the level of details

7 Steps of Development

- 1. Identify the “product” - focus of the roadmap,*
- 2. Identify critical system requirements and targets,*
- 3. Specify major technology areas,*
- 4. Specify the technology drivers and targets,*
- 5. Identify technology alternatives and timelines,*
- 6. Recommend technology alternatives to be pursued*
- 7. create the technology roadmap*

Evolution



Identify the “product” that will be the focus of the roadmap

- Common product needs are identified and should be agreed on by all the participants.
- Acceptance of all groups for the process.
- In case of uncertainty of the product needs **scenario-based planning** can be used to determine the common product needs.

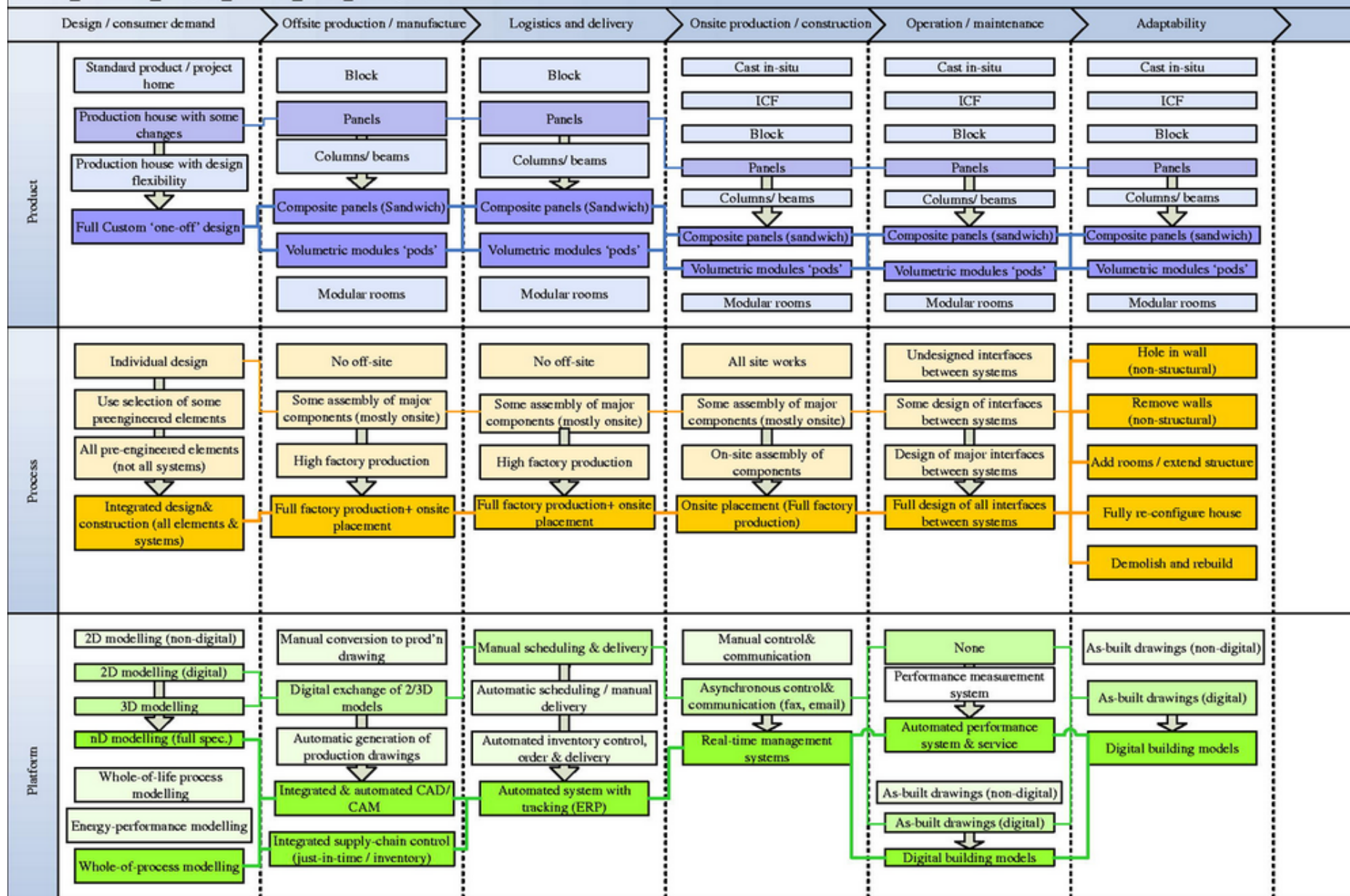
Identify the critical system requirements and their targets

- **Critical system requirements** provide the overall framework for the technology roadmap.
- Requirements can have targets like reliability and costs.

Specify the Major Technology Areas

- These are the areas which can help achieve the critical system requirements
- Technology areas may include several different technologies

Concrete Prefabricated Housing via Advances in Systems Technologies (concrete PHAST)



Specify the technology drivers and their targets

- Critical system requirements are transformed into technology drivers (with targets)
- Drivers are the critical variables that will determine which technology alternatives are selected.
- Drivers depend on the technology areas but they relate to how the technology addresses the critical system requirements.

Identify Technology Alternatives and their Timelines

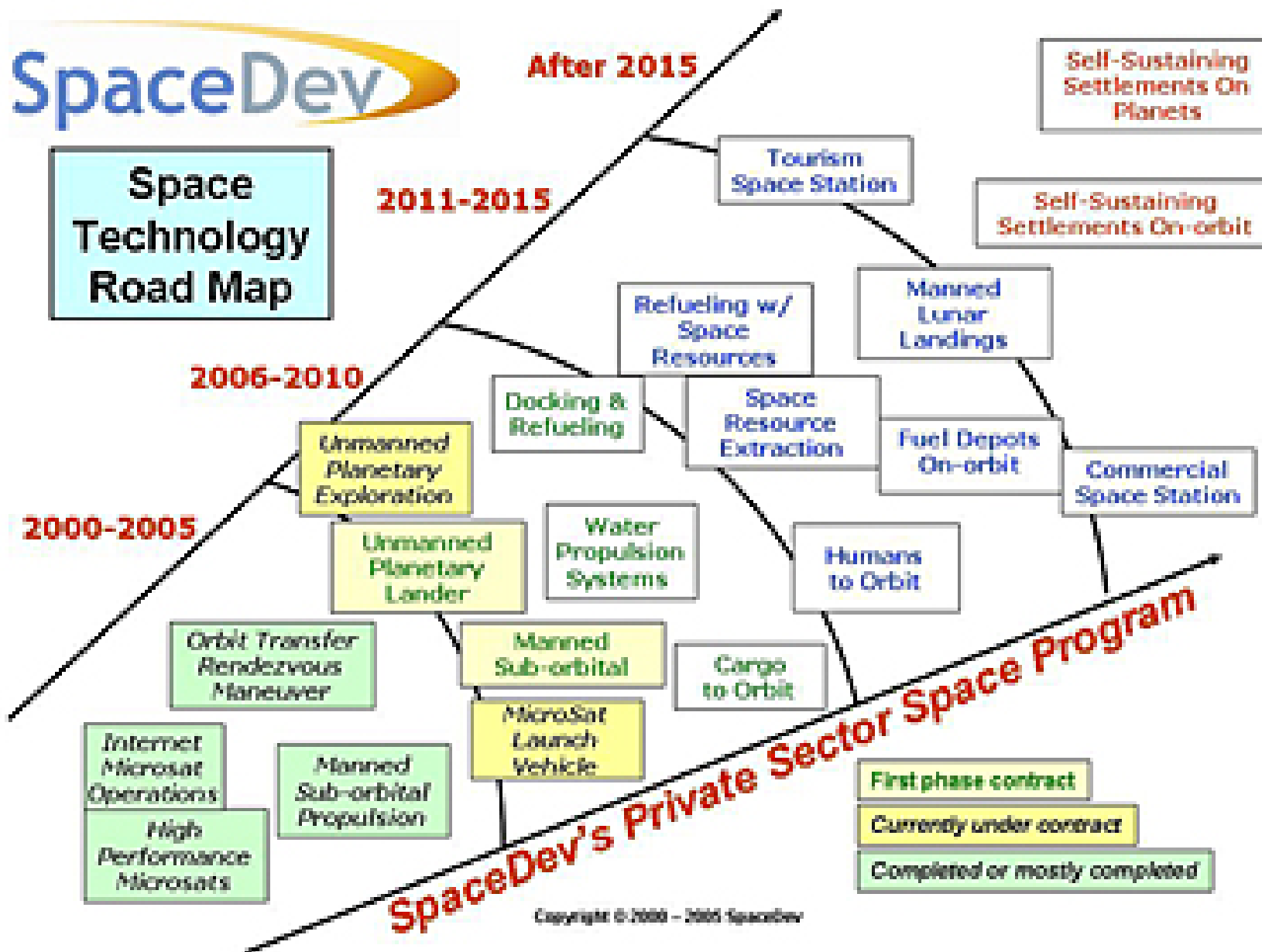
- Technology drivers and their targets are specified and the technology alternatives that can satisfy those targets are specified
- For each of the alternatives a timeline is estimated for how it will mature with respect to the technology driver targets.

Recommend the technology alternatives that should be pursued

- Alternatives may differ in costs and timeline
- These alternatives will be pursued
- Trade-offs are made between different alternatives for different targets, performance over costs and even target over target.



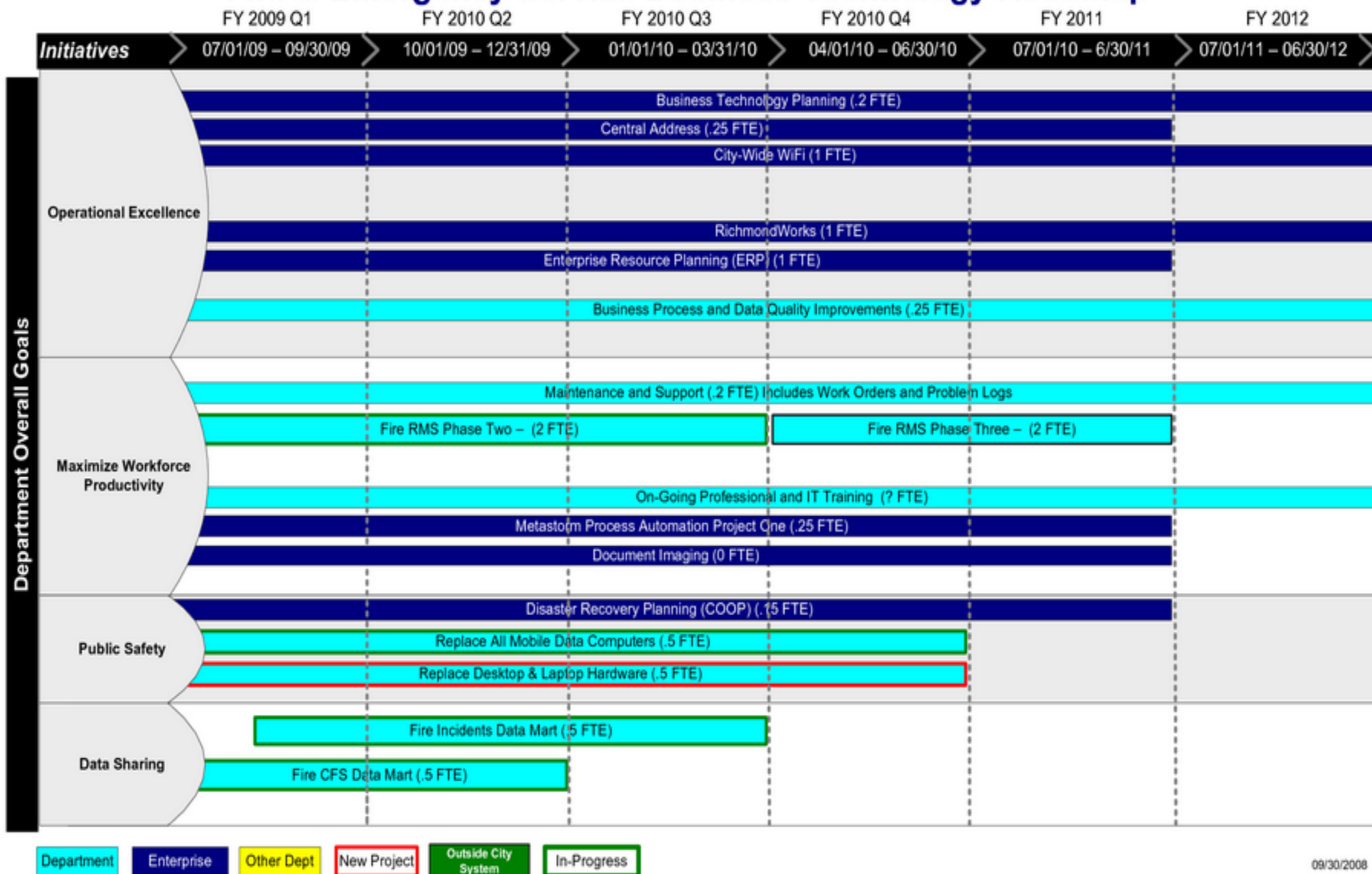
Space Technology Road Map



Technology Roadmap Report

- Identification and description of each technology area
- Critical factors
- Unaddressed areas
- Implementation recommendations
- Technical recommendations.

Fire & Emergency Service Business Technology Roadmap

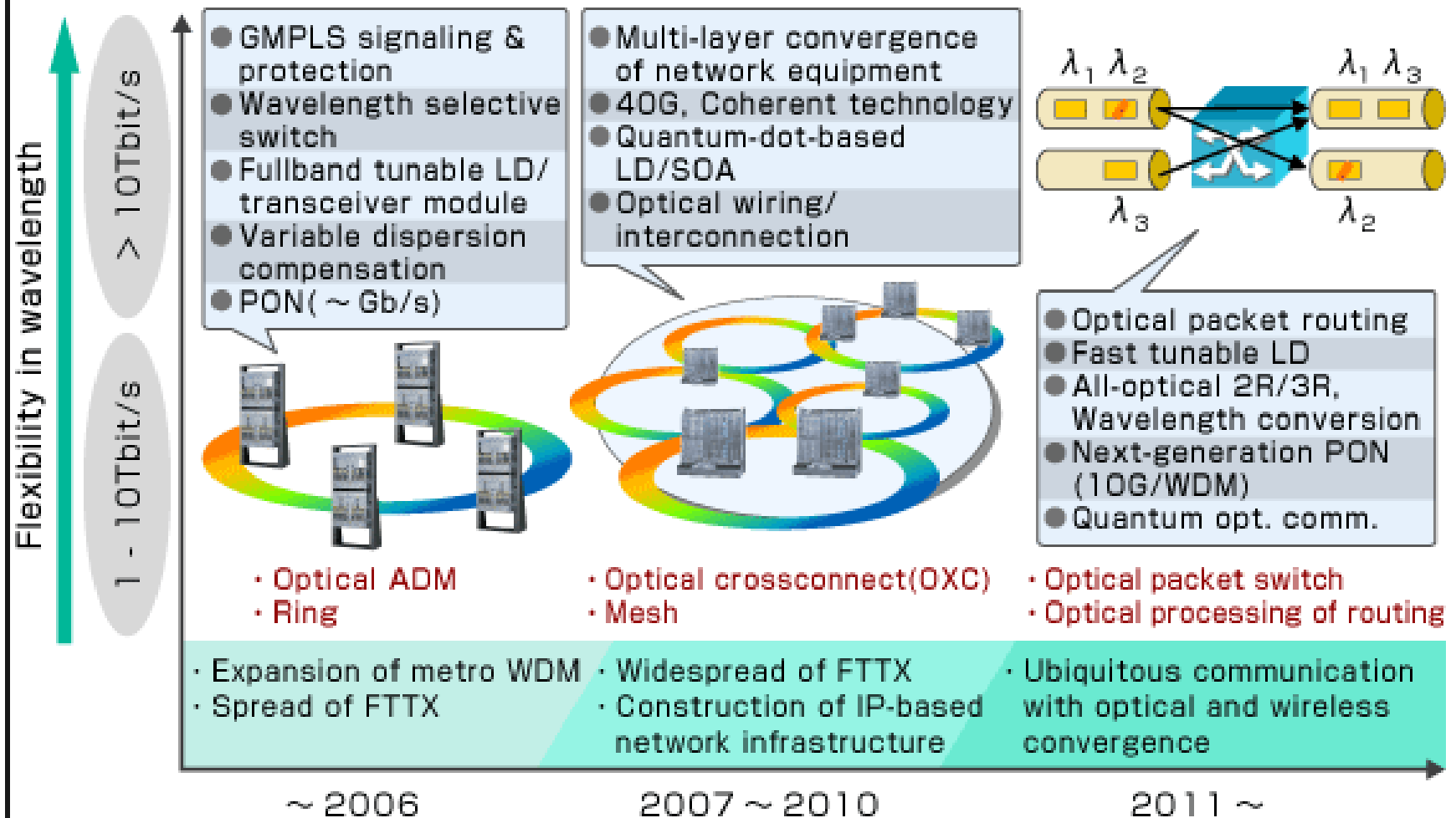


Knowledge and skills required

- Requires certain knowledge and skills
- Some participants must know the process of technology roadmapping.
- Group-process and interpersonal skills required
- Process includes a lot of discussion
- May need a facilitator.



Roadmap of FUJITSU Photonics Technology



IBM Semiconductor technology roadmap

View the Power.org Power Architecture Processor Roadmap at <http://www.power.org/resources/devcorner/roadmap>.



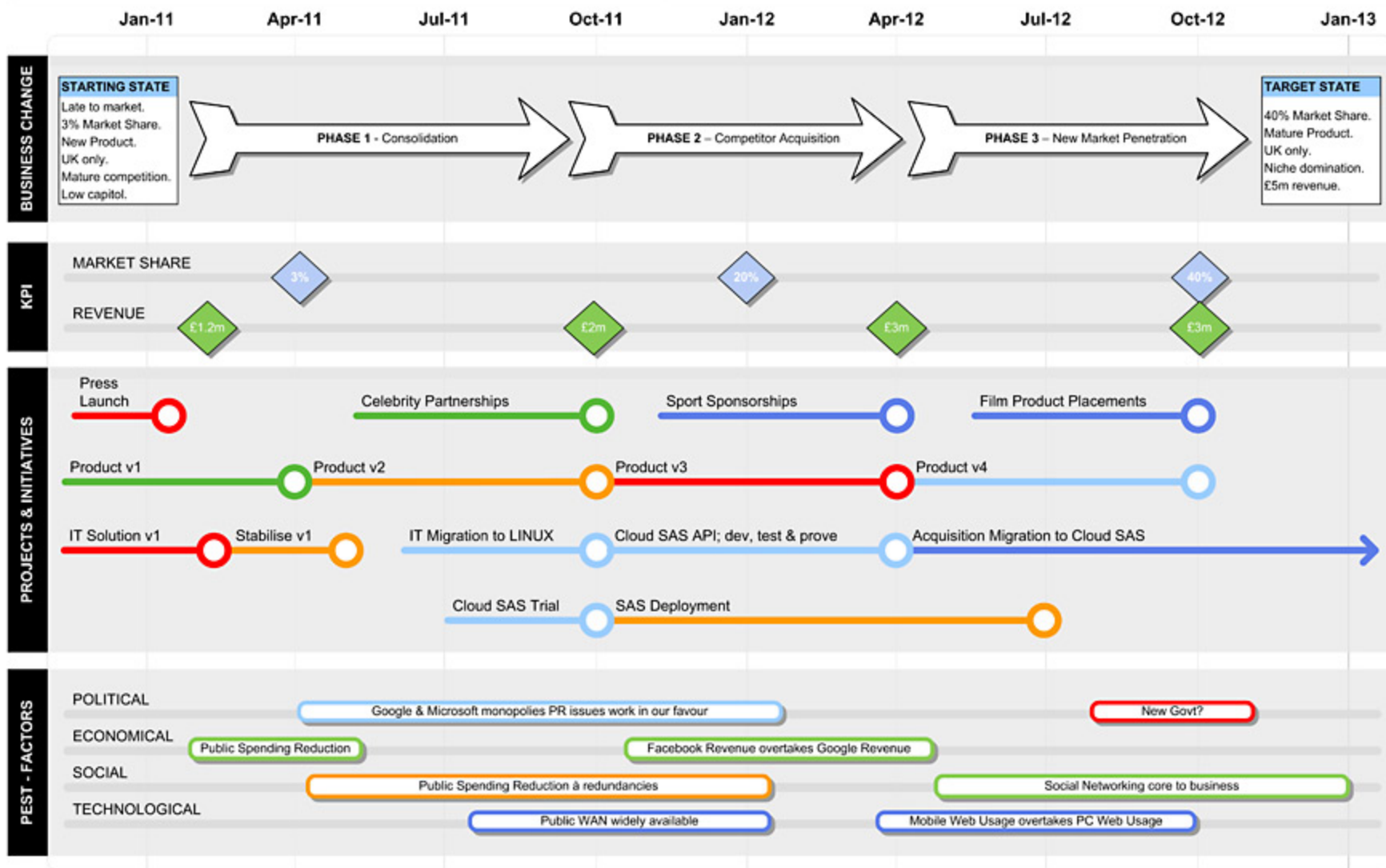
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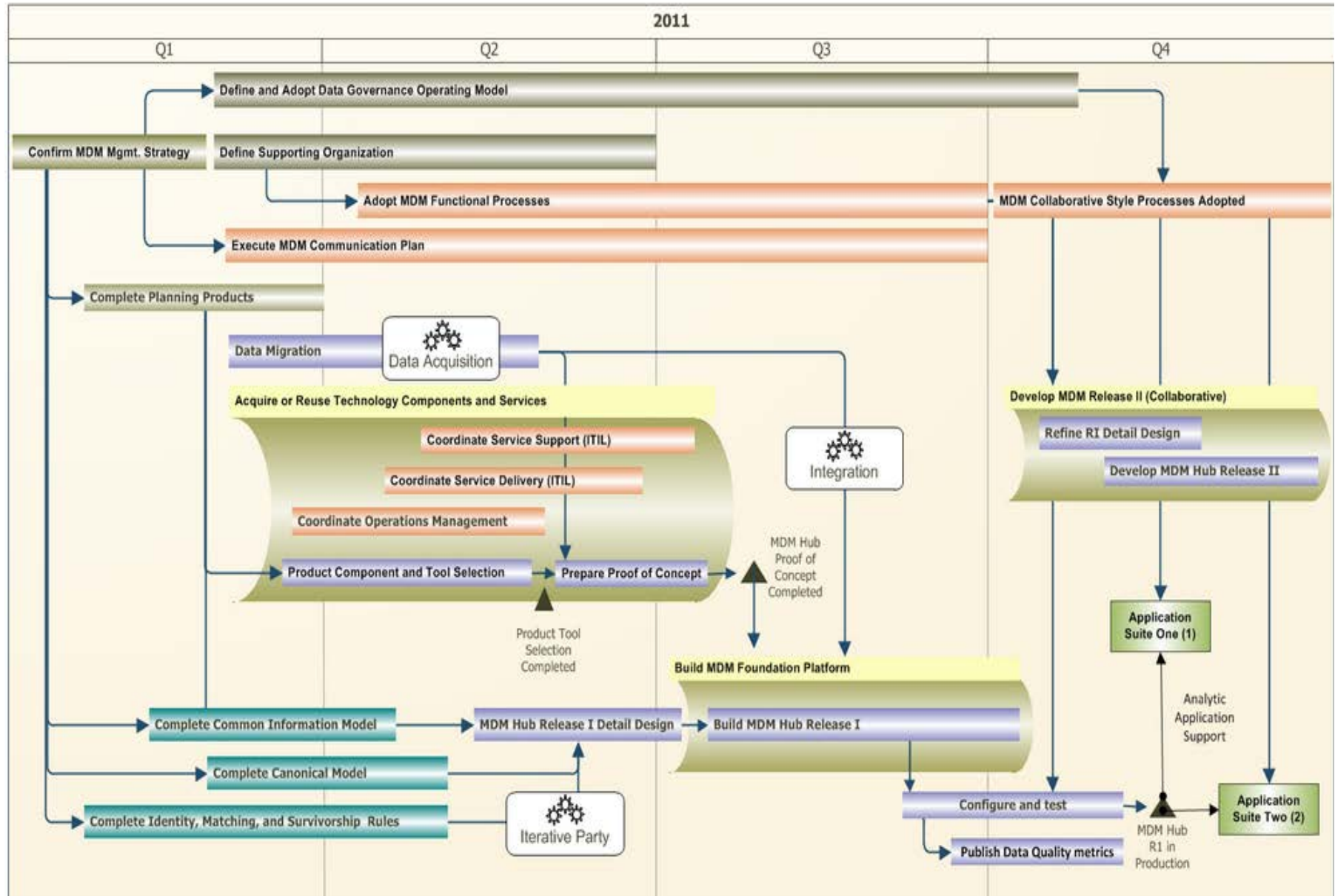
Version 2

Roadmap Template

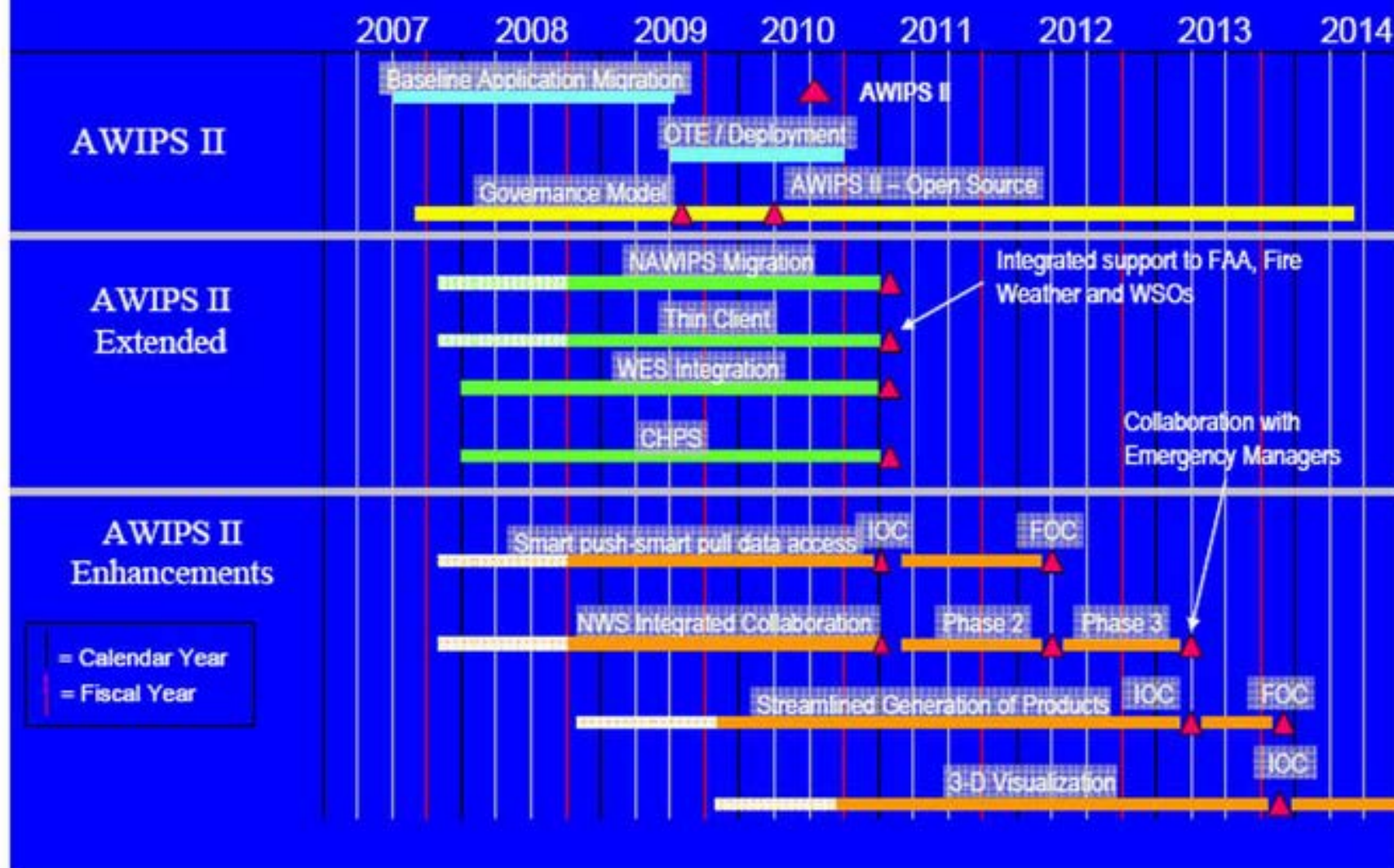
subtitle

Saturday, 13 November 2010

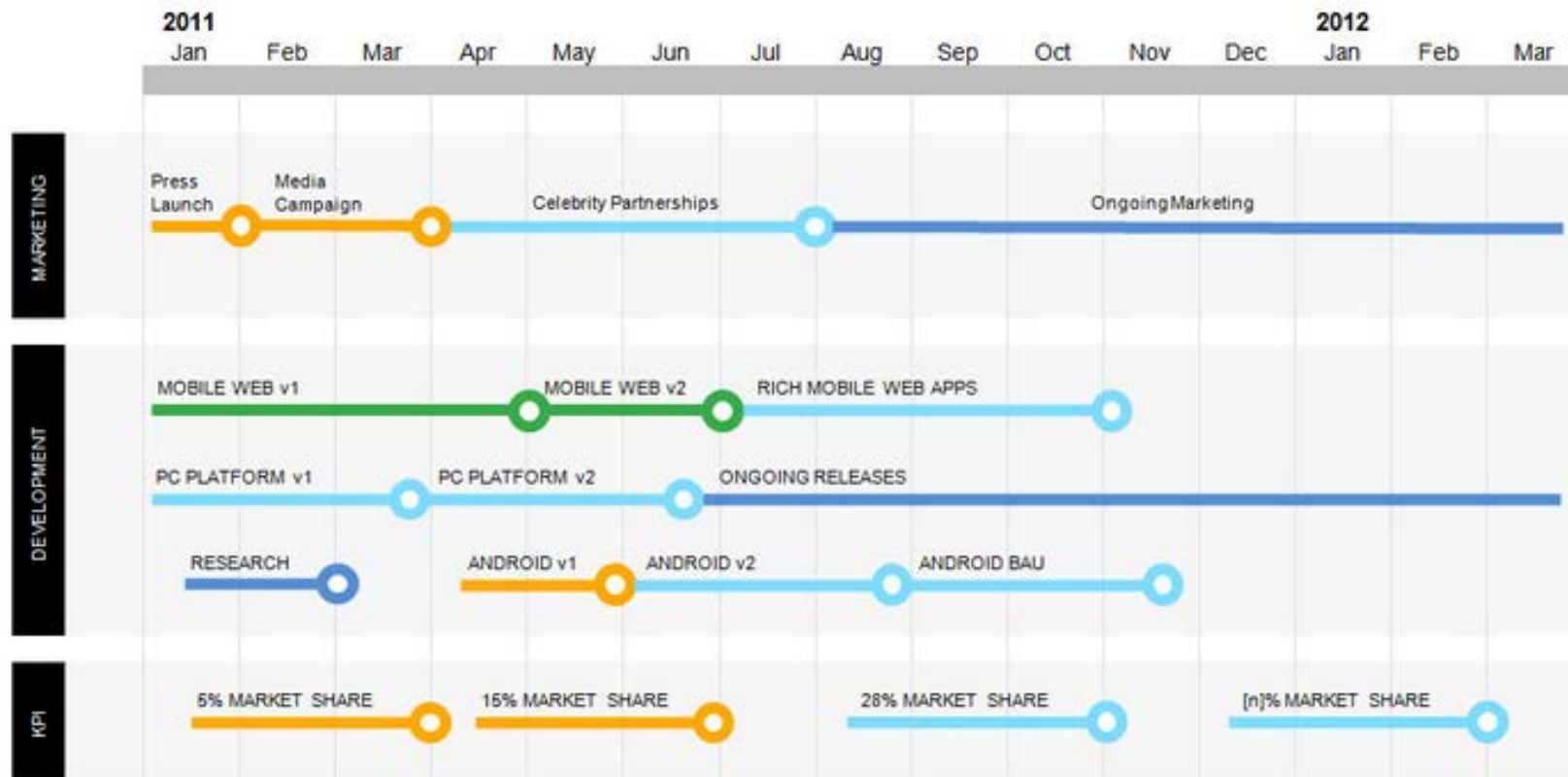


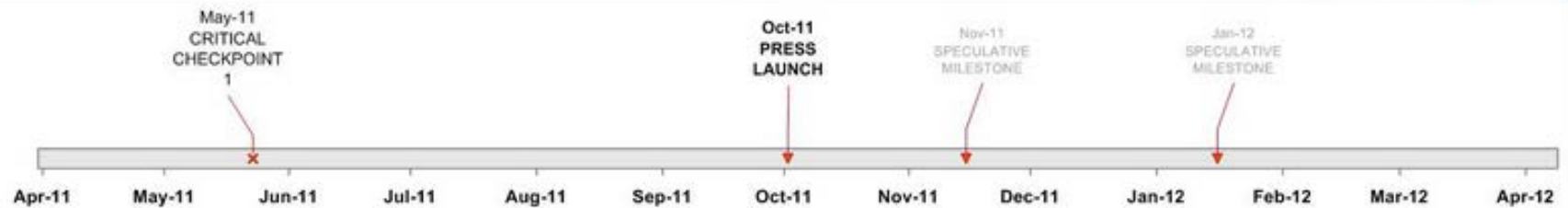


AWIPS Technology Infusion Roadmap



Product Roadmap





SIMPLE CONDIMENTS



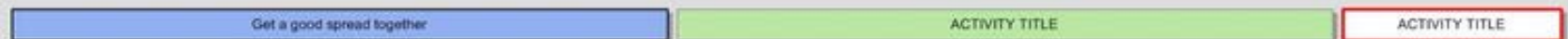
SAUCES



CHILLIES



VEG



PROCURE SOME CHEFS



CAVEATS

- * Point 1
- * Point 2
- * Point 3
- * Point 4

RESOURCES

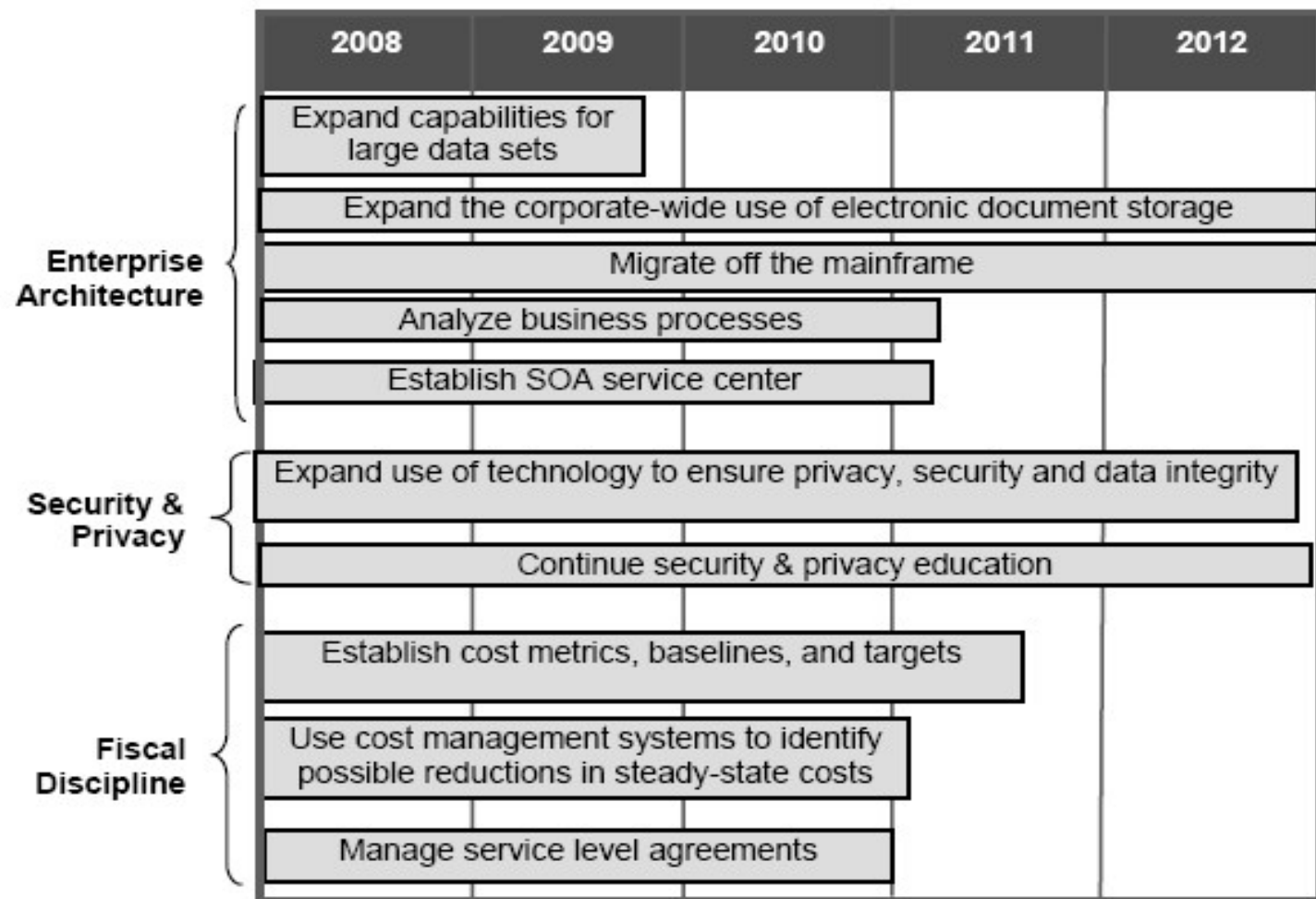
- * Point 1
- * Point 2
- * Point 3
- * Point 4

PARTNERSHIPS

- * Point 1
- * Point 2
- * Point 3
- * Point 4

Useful or Not?

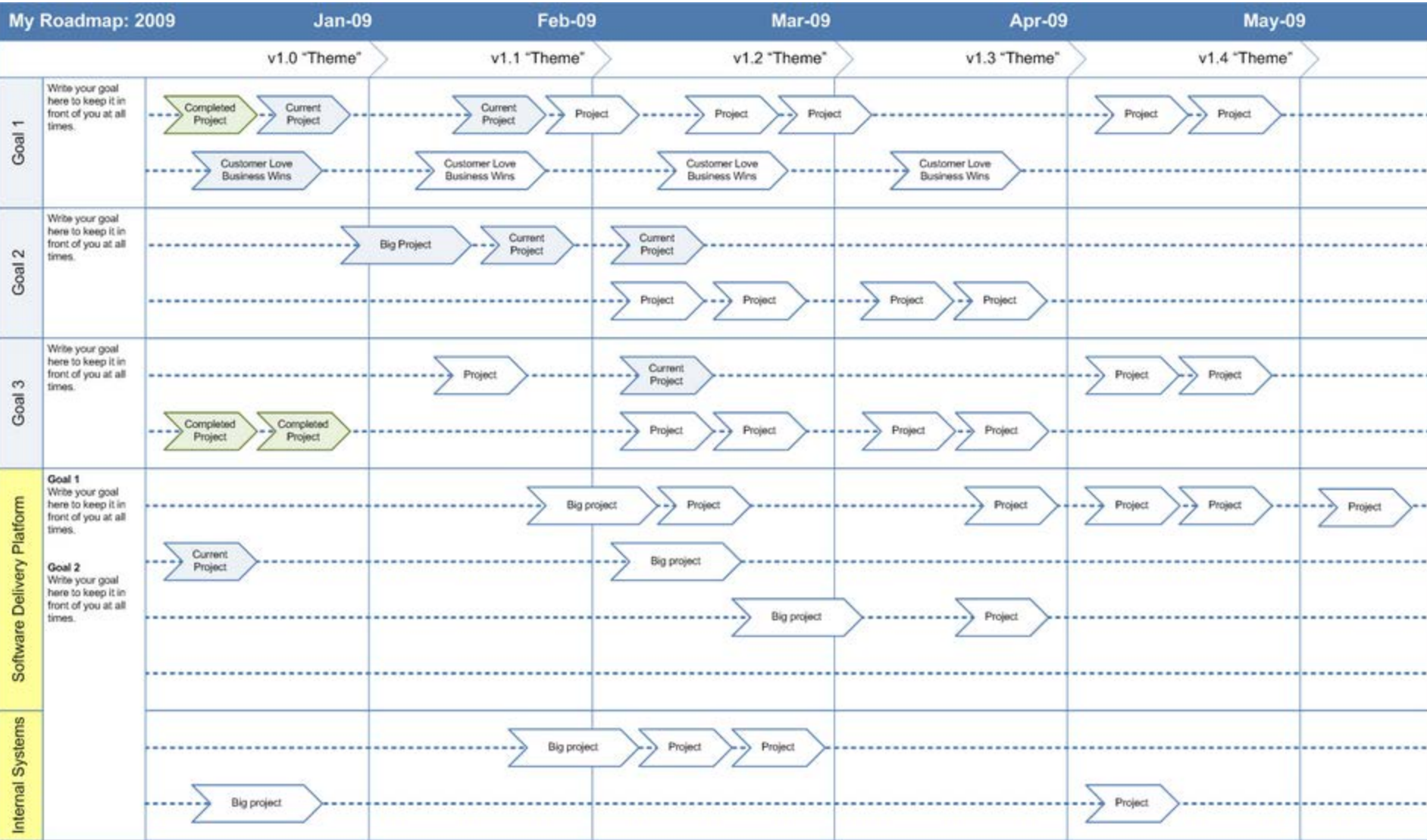
Discussion



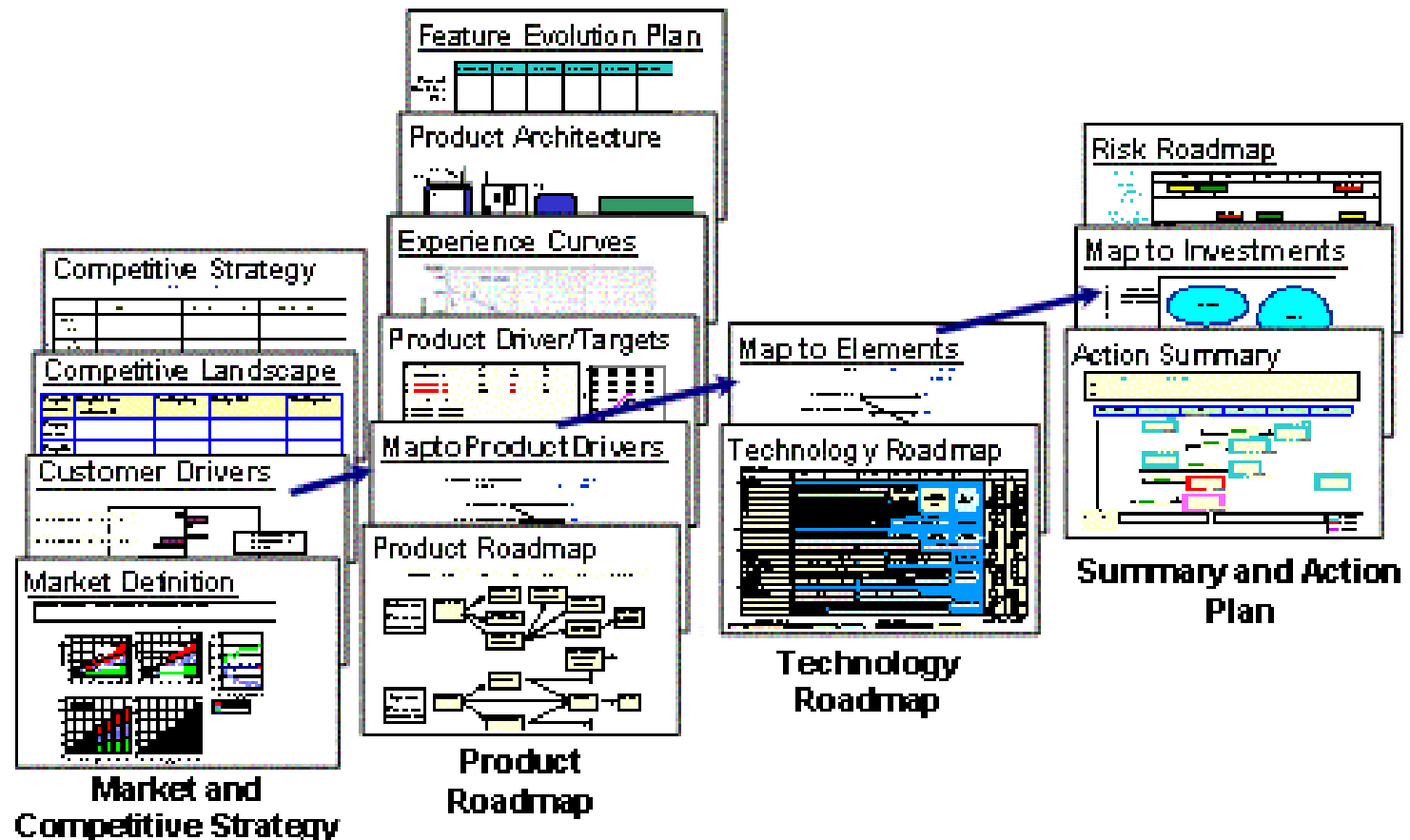
Roadmap Questionnaire

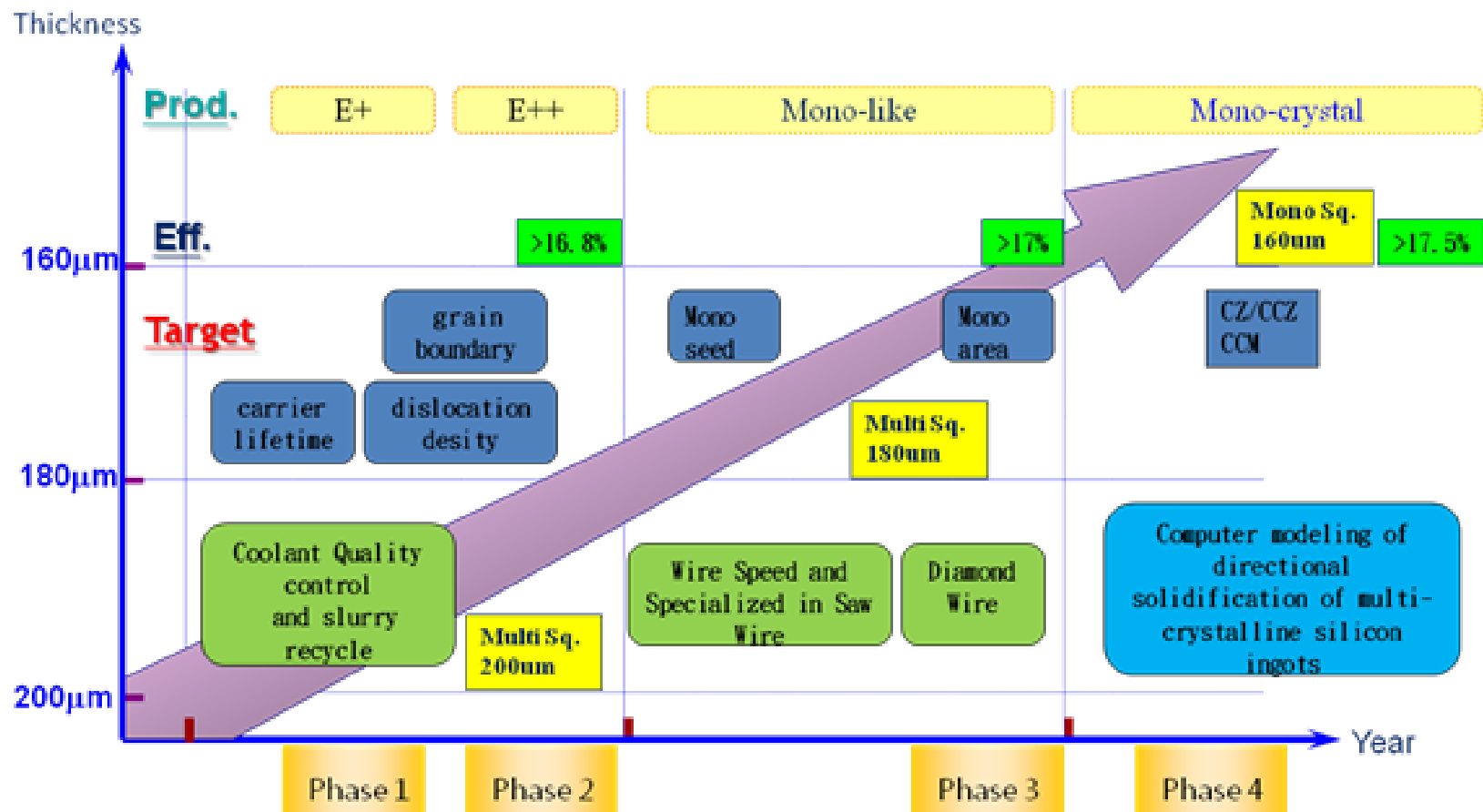
Your Company name:					
Field your company is working in: (please tick a box)	materials	tools	technology	wafer, cells or modules	other, please state
I would like to get more involved in the roadmap activity	yes	no			
I would like to get information, if there are any news	yes	no			
Name :					
email for contact:					

Roadmap Forum - give us your view										
Your priority 1 important 2 interesting 3 not needed		2009	2010	2011	2013	2015	2017	2020	Remarks	Your comment
Materials										
Wafer Geometry										
	Thickness mono [µm]	180	180	160	140	130	110	100	Average of as cut thickness, measured according to Din EN 50513,	
	Your view on data									
	Thickness multi incl. ribbon [µm]	180	180	160	145	135	120	100		
	Your view on data									
	TTV [µm]	27.5	27.5	25	17.5	17.5	15	12.5	Total thickness variation measured according to Din EN 50513	
	Your view on data									
	Larger wafer than 156mm x 156mm	0	0	0	0	1	1	1		Yes= 1/ No=0
	Your view on data								Please suggest size in comment.	
	Status rating wafer	0	0	0	1	2	3	3	see legend below	
	Your status rating									
	Heavy metals in metallization ink (yes/no)	1	1	0	0	0	0	0	Yes= 1/ No=0 heavy metals shall be added on purpose. Traces smaller 0,001% shall be	
	Your view									
	Reduce Ag [g/cell]	Ag should be significantly reduced from 2013 on								
	Your view									
	Which materials to replace Ag ?									
	Additionally								Should there be additional parameter like e.g. minority carrier lifetime for wafer or like e.g. replacement of hazardous chemicals ? Please make your suggestion	
	Your view									
	Your view									
	Your view									
	Your view									
Process										
	mechanical yield loss	2.5	2	1.5	1.3	1.14	0.9	0.9	percentage of incoming products including handling that exhibit mechanical damage after process referring to above given wafer	
	Status rating yield loss with colour	0	0	0	1	2	3	3		
	Your view on status rating									see legend below
	Your view on data									
	Uptime Semi E10									
	chemical processes [%]	96	96	96	97	97	97	97		



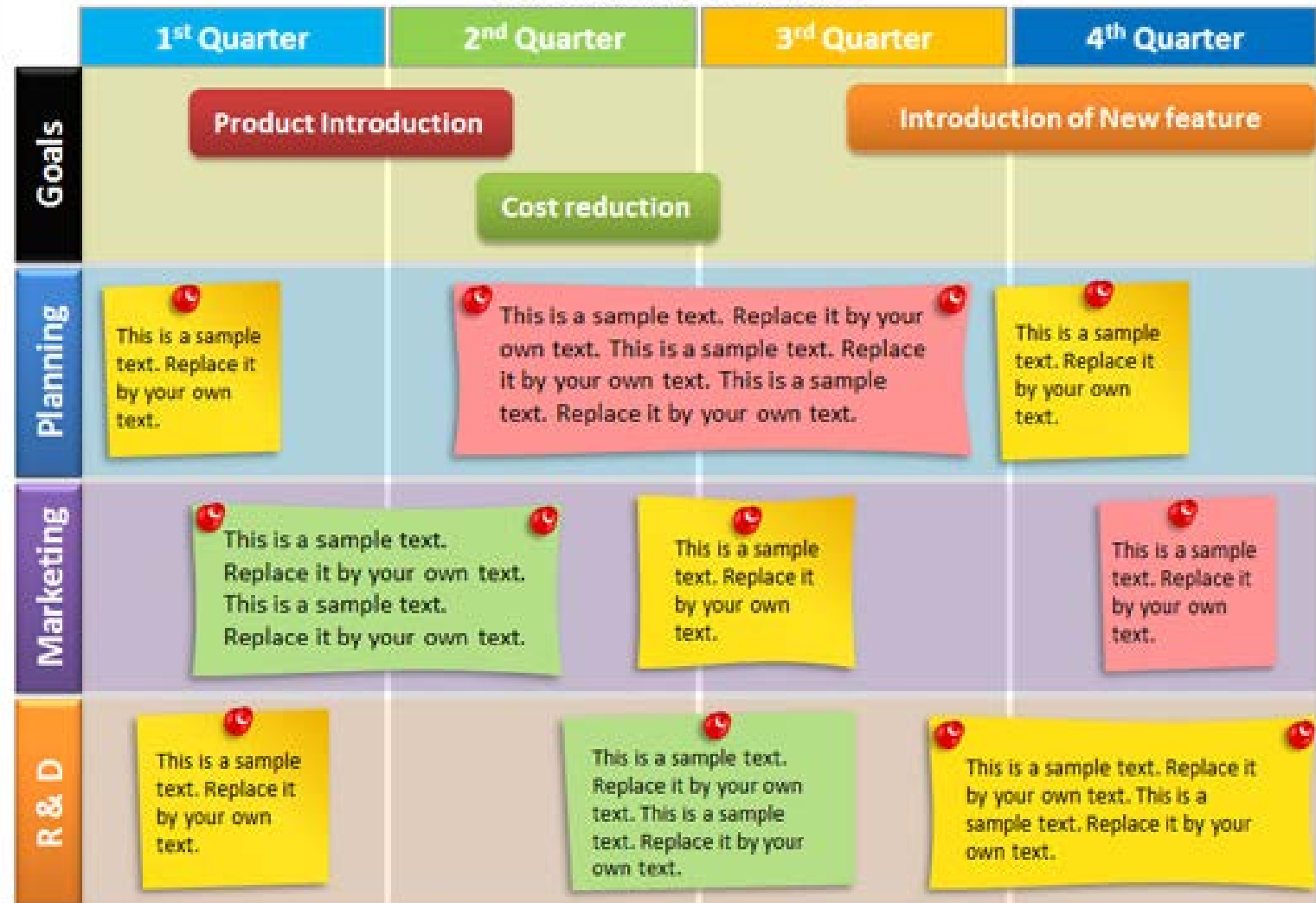
Product-Technology Roadmap

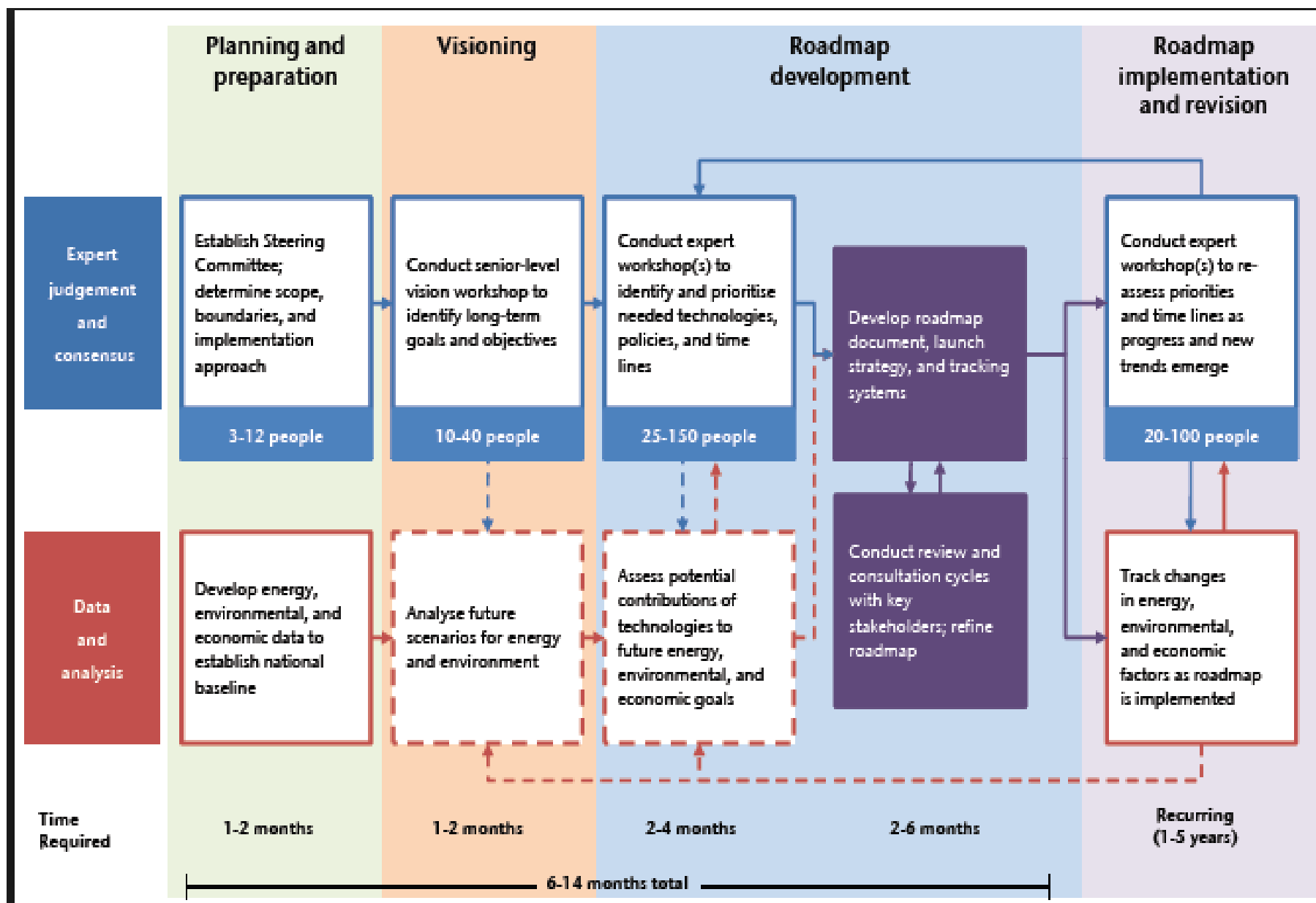


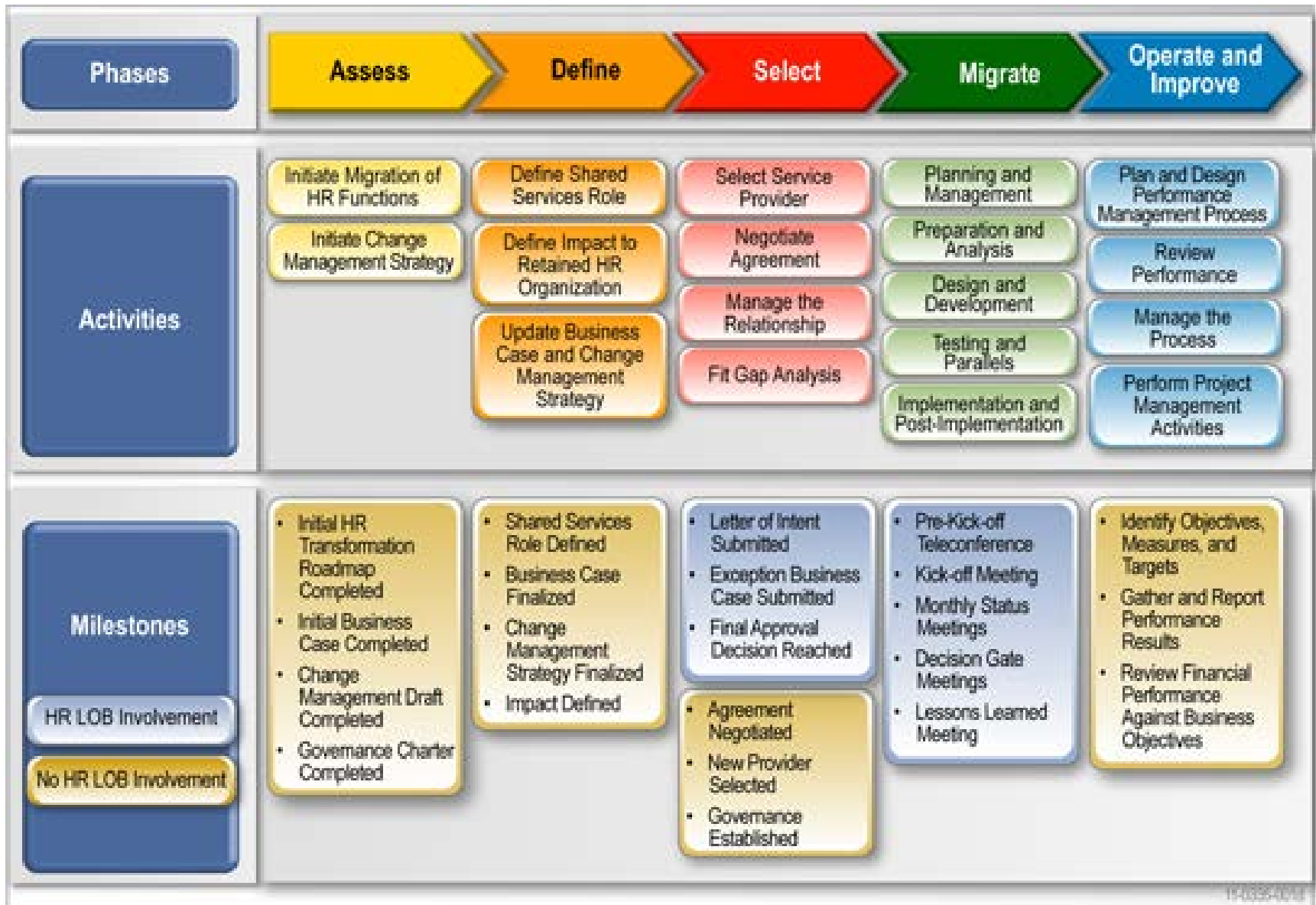


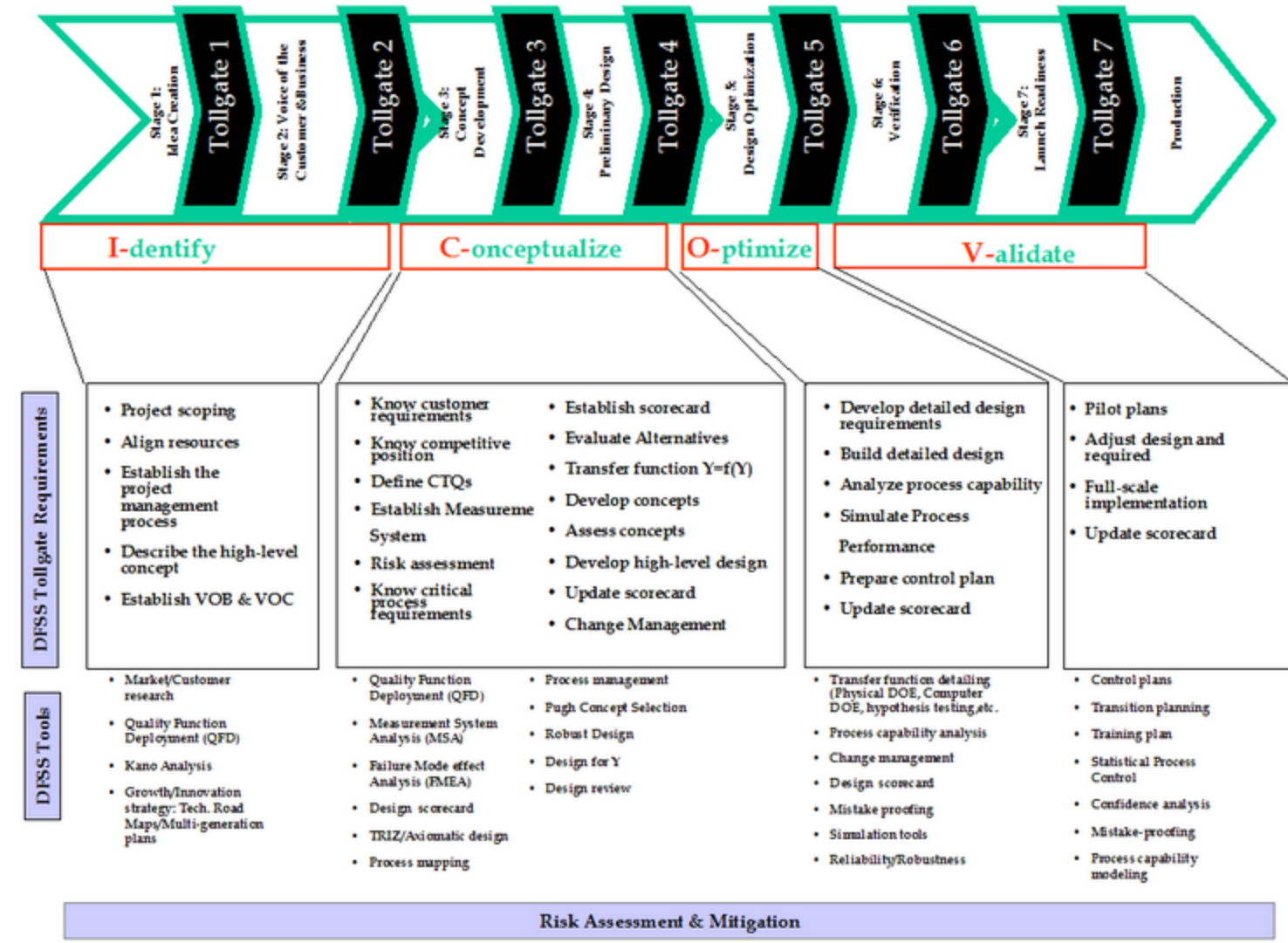
Agile Roadmap

Project Title or Product Name









Development Tools

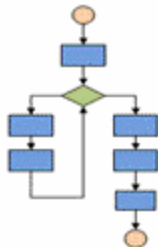
Visual Studio Tools
for Office 3.0

Visual Studio 2008

InfoPath 2007

SharePoint
Designer 2007

LOB Workflow



Workflow In the 2007 Microsoft Office System

